SEMI-CONDUCTOR INDUSTRY

::CMP Machine::

POLI 400

POLI-400 model is high reliability CMP tester which improves from POLI-380 with easy handling and low cost of ownership. This equipment ensure more effective process development. The dramatically reduced time of process development allows for a much faster time-to-research and market.

Features

- Desk-top CMP Machine for R & D
- Stable repeatability (WTWNU < 5%)
- High rigidity, High flatness
- Head Oscillation (-25mm ~ +25mm)
- Two supply systems (DIW + Slurry)

Specification

- Head, Table : Rotational motion
- Size : 740W 890D 760H mm
- Workpiece : Max 6 inch Wafer or MEMS Structure Surface or Coupon Wafer
- Table Size : 400mm
- Pressing Method : Air pressing by electric air regulator (range 60 ~ 700g/cm2 for 4")
- Head Type : 4 inch type, 6 inch type, Required type (Changeable)
- Process : Automatic Sequence, Dry-in / Wet-out
- PLC Control (under developing PC Control)
- Conditioner: Ring type diamond Conditioner (attachable to head)
- Head/Table Velocity : max 100rpm
- Head Oscillation

Model	POLI-400
Platen Diameter	Φ 400mm
Platen Speed	0-200 rpm
Wafer Size	Max φ 150 mm
Work Head Speed	0-200 rpm
Pressure	100 g/cm²~ 700 g/cm²
Dimension (WxDxH)	700x920x990 (mm)
Weight	400kg

POLI-500

POLI-500 model can be applicable up to 200mm wafer as well as coupon, 100mm and 150mm wafer. Automatic process and in-situ conditioning realize most similar process with actual CMP process. This equipment ensure a very effective process, consumable development and research. The dramatically reduced time of research or development allows for a much faster time-to-research and market.

Features

- 200mm CMP Machine for R & D
- Stable repeatability (WTWNU < 5%)
- Applicable from coupon wafer to 200mm
- In-situ or ex-situ conditioning
- Semi-pneumatic pressing method
- High rigidity, High flatness

Specification

- Head, Table : Rotational motion
- Size : 740W 890D 760H mm
- Workpiece : Max 6 inch Wafer or MEMS Structure Surface or Coupon Wafer
- Table Size : 400mm
- Pressing Method : Air pressing by electric air regulator (range 60 ~ 700g/cm2 for 4")
- Head Type : 4 inch type, 6 inch type, Required type (Changeable)
- Process : Automatic Sequence, Dry-in / Wet-out
- PLC Control (under developing PC Control)
- Conditioner: Ring type diamond Conditioner (attachable to head)
- Head/Table Velocity : max 100rpm
- Head Oscillation
- Metal CMP applicable

Model	POLI-500
Platen Diameter	Φ 500mm
Platen Speed	0-90 rpm
Wafer Size	φ 100 mm, φ 200 mm
Work Head Speed	0-90 rpm
Pressure	100 g/cm² ~ 500 g/cm²
Dimension (WxDxH)	700x920x990 mm
Weight	400kg

POLI-1200

Can be applicable to CMP of wafer. Automatic process and in-situ conditioning Realize most similar process with actual CMP process. This equipment ensure a Very effective process, consumable development and research. The dramatically Reduced time of research and market.

Features

- 200mm Wafer CMP Machine
- Stable Repeatability
- Applicable form coupon wafer to 200mm wafer
- in-situ of ex-situ conditioning
- Self-weight pressing method (Semi-pneumatic pressing method)
- High Rigidity
- High Flatness

Specification

Model	POLI-1200
Wafer Size	Φ 1200mm
Wheel Driving Motor	11kW, 0~90rpm
Condition Ring	Φ 560 mm
Max Pressure	120 kg/bar
Dimension (WxDxH)	1,800x1,530x2,150 (mm)
Weight	2,800kg